

**METHOD AND STRUCTURE FOR PRODUCING Z-AXIS  
INTERCONNECTION ASSMEBLY OF PRINTED WIRING BOARD  
ELEMENTS**

**Abstract of the Disclosure**

5           A method of forming a core for and forming a composite wiring board. The  
core has an electrically conductive coating on at least one face of a dielectric  
substrate. At least one opening is formed through the substrate extending from one  
face to the other and through each conductive coating. An electrically conductive  
material is dispensed in each of the openings extending through the conducting  
10       coating. At least a portion of the surface of the conductive coating on one face is  
removed to allow a nub of the conductive material to extend above the substrate face  
and any remaining conductive material to thereby form a core that can be electrically  
joined face-to-face with a second core member or other circuitized structure.